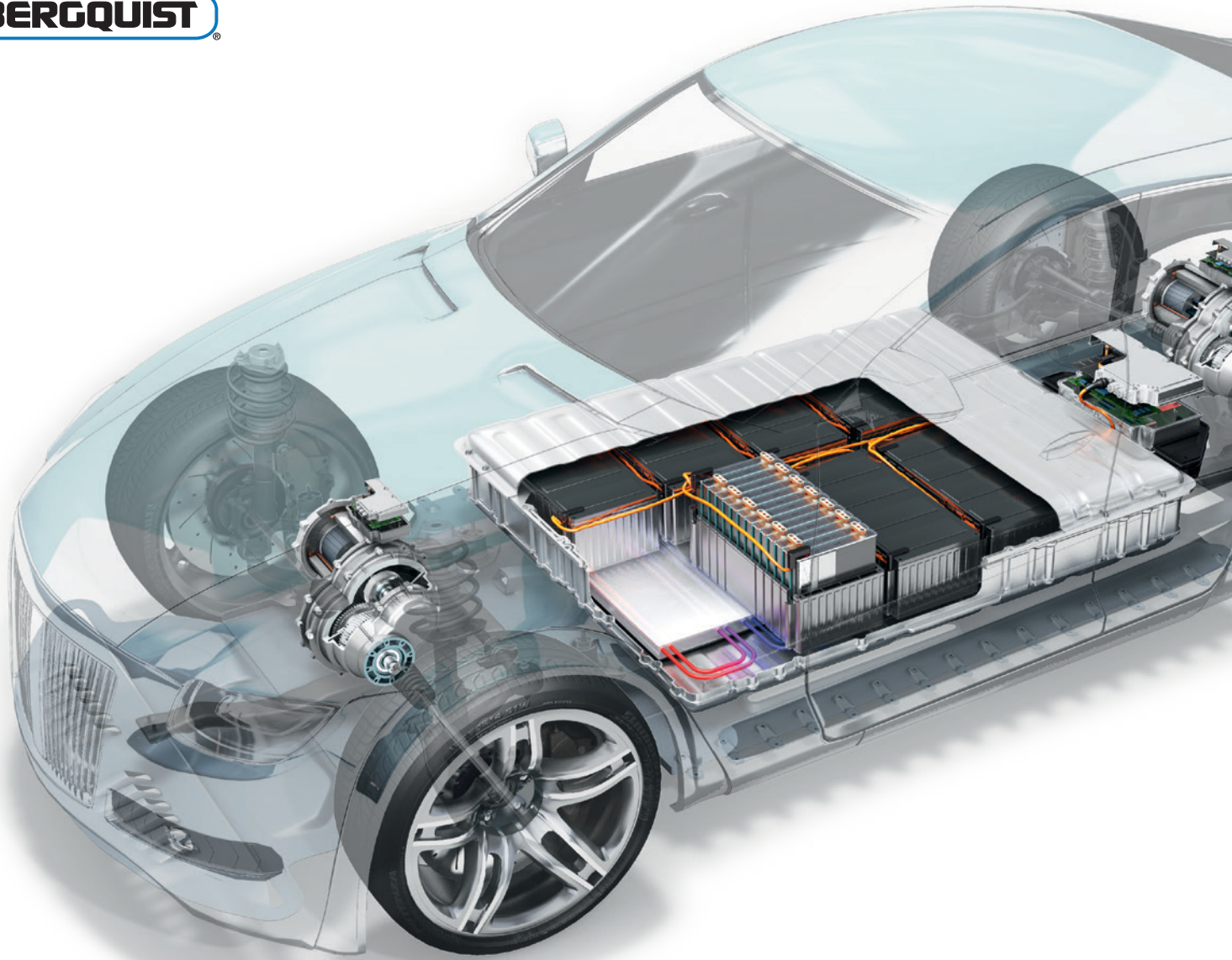


BERGQUIST



BERGQUIST® GAP FILLER TGF 3010APS

SILICONE-FREE GAP FILLER WITH A HIGH DISPENSE RATE

BERGQUIST® GAP FILLER TGF 3010APS from Henkel is a non-silicone, two-part, room temperature curable gap filler suitable for use in high-throughput assembly applications. With a 3.0 W/m•K thermal performance, it provides an excellent silicone-free solution critical to power storage applications using lithium ion batteries. This material is an exceptional choice for use in automotive and consumer applications.

Henkel



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PROPERTIES	TYPICAL VALUE	TEST METHODS
Thermal conductivity	3.0 W/m•K	ASTM D5470
Density	3.0 g/cc	ASTM D792
Hardness (shore 00)	75	ASTM D2240
Viscosity	460 mPa•s	ASTM D2196
Gel time	240 min.	ASTM D4473
Full cure	24 hr.	ASTM D4473
Dielectric strength	14 kV/mm (VAC)	ASTM D149
Volume resistivity	1.OE+6 Ω•m	ASTM D257
Application temperature	-40°C to 80°C	N/A
Mixing ratio	1:1 by volume	—

TYPICAL APPLICATIONS

- » Automotive power storage
- » Silicone-sensitive applications
- » Processes requiring high dispense rate
- » Applications requiring high thermal transfer and low compressive stress

FEATURES & BENEFITS

- » High thermal conductivity: 3.0 W/m•K
- » Dispensable liquid, two-part silicone-free gap filler
- » Room temperature curing
- » Extremely high dispense rate: > 40 cc/sec
- » Low compression stress during assembly
- » Form stability after dispense

CONFIGURATIONS AVAILABLE

BERGQUIST® GAP FILLER TGF 3010APS is available in the following configurations:

Cartridges	200 cc	400 cc	1200 cc
Pail Kits	6 gallons	10 gallons	
Drum Kits	120 liters		

Reach out to our experts to partner up in solutions for thermal battery cooling.

Across the Board,
Around the Globe. 
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